

14020 Rec'd-CTPTO 26 MAY 2006

Case No. 10808/330 (In1344WOUS)

In re Application of:

Examiner:

Serial No.: Not Yet Assigned

Group Art Unit No.:

For METHOD FOR ELECTROPLATING
AND CONTACT PROJECTION
ARRANGEMENT

Alexandria, Virginia 22313-1450

§§1.97-1.98, and more particularly in accordance with 37 C.F.R. §1.97(b), Applicants hereby cite the following references:

DOCUMENT NUMBER	DATE/ DATE OF PUBLICATION	NAME/COUNTRY
US 2004/0018660 A1	01/29/2004	Kim et al.
US 2002/0072215 A1	06/13/2002	Furuya
6,316,831 B1	11/13/2001	Wang
WO 03/044246 A1	05/30/2006	PCT
EP 1 148 548 A2	10/24/2001	EPO
EP 0 547 815 B1	03/12/1997	EPO
EP 0 261 799 A1	03/30/1988	EPO
FR 2 502 399	09/24/1982	France
GB 2 095 904 A	10/06/1982	Great Britain
02224336	09/06/1990	Japan
56105653	08/22/1981	Japan

Jang et al., "CrCu Based UBM (Under Bump Metallization) Study With Electroplated Pb/63Sn Solder Bumps-Interfacial Reaction and Bump Shear Strength," IEEE Transactions on Components and Packaging Technologies, Vol. 26, No. 1, March 2003, pp. 245-254.

Reid et al., "Factors Influencing Damascene Feature Fill Using Copper PVD and Electroplating," *Solid State Technology*, July 2000, pp. 86-88, 92, 96, 98, 103.

ALL REFERENCES CONSIDERED EXCEPT WHERE LINED THROUGH. /L.V./

10580347/40: 1795
MAY 2006

Applicants are enclosing Form PTO-1449 (one sheet), along with a copy of cited references A4-A13. Applicants respectfully request the Examiner's consideration of the above references and entry thereof into the record of this application.

Also enclosed is a copy of an Office Action dated July 27, 2004 from the corresponding German Application (in the German language).

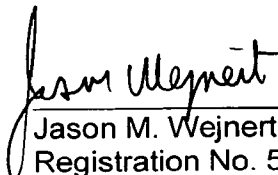
Also enclosed is a copy of the International Search Report dated March 1, 2005 for the corresponding PCT Application No. WO2004/052999.

FR 2 502 399 discloses a semiconductor device having low resistance connection to a portion thereof carrying substantial current. A non-certified English translation of the Abstract is enclosed herewith. Applicants have also cited corresponding Great Britain Patent No. 2 095 904 A.

By submitting this Statement, Applicants are attempting to fully comply with the duty of candor and good faith mandated by 37 C.F.R. §1.56. As such, this Statement is not intended to constitute an admission that any of the enclosed references, or other information referred to therein, constitutes "prior art" or is otherwise "material to patentability," as that phrase is defined in 37 C.F.R. §1.56(a).

Applicants have calculated no fee to be due in connection with the filing of this Statement. However, the Director is authorized to charge any fee deficiency associated with the filing of this Statement to a deposit account, as authorized in the Transmittal accompanying this Statement.

Respectfully submitted,



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1AP20 Rec'd PCT/PTO 26 MAY 2006

FORM PTO-1449	SERIAL NO. Not Yet Assigned	CASE NO. 10808/330 (In 1344) GROUP ART UNIT Not Yet Assigned
LIST OF PATENTS AND PUBLICATIONS FOR APPLICANT'S INFORMATION DISCLOSURE STATEMENT	FILING DATE May 26, 2006	
	APPLICANTS: Helneder et	

REFERENCE DESIGNATION

U.S. PATENT DOCUMENTS

EXAMINER INITIAL		DOCUMENT NUMBER <small>Number-Kind Code (if known)</small>	DATE	NAME	CLASS/ SUBCLASS	FILING DATE
	A1	US 2004/0018660 A1	01/29/2004	Kim et al.		
	A2	US 2002/0072215 A1	06/13/2002	Furuya		
	A3	6,316,831 B1	11/13/2001	Wang		

FOREIGN PATENT DOCUMENTS

EXAMINER INITIAL		DOCUMENT NUMBER <small>Number-Kind Code (if known)</small>	DATE	COUNTRY	CLASS/ SUBCLASS	TRANSLATION YES OR NO
	A4	WO 03/044246 A1	05/30/2006	PCT		
	A5	EP 1 148 548 A2	10/24/2001	EPO		
	A6	EP 0 547 815 B1	03/12/1997	EPO		
	A7	EP 0 261 799 A1	03/30/1988	EPO		
	A8	FR 2 502 399	09/24/1982	France		Abstract only
	A9	GB 2095904	10/06/1982	Great Britain		
	A10	02224336	09/06/1990	Japan		Abstract only
	A11	56105653	08/22/1981	Japan		Abstract only

EXAMINER INITIAL	OTHER ART – NON PATENT LITERATURE DOCUMENTS (Include name of author, title of the article (when appropriate), title of the item (book, magazine, journal, serial, symposium, catalog, etc.), date page(s), volume-issue number(s), publisher, city and/or country where published.	
A12		Jang et al., "CrCu Based UBM (Under Bump Metallization) Study With Electroplated Pb/63Sn Solder Bumps-Interfacial Reaction and Bump Shear Strength," IEEE Transactions on Components and Packaging Technologies, Vol. 26, No. 1, March 2003, pp. 245-254.
A13		Reid et al., "Factors Influencing Damascene Feature Fill Using Copper PVD and Electroplating," <i>Solid State Technology</i> , July 2000, pp. 86-88, 92, 96, 98, 103.

EXAMINER	/Luan V. Van/ (03/02/2009)	DATE CONSIDERED
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EXAMINER: Initial if reference considered, whether or not citation is in conformance with MPEP 609; Draw line through citation if not in conformance and not considered. Include copy of this form with next communication to applicant.

ALL REFERENCES CONSIDERED EXCEPT WHERE LINED THROUGH. /L.V./